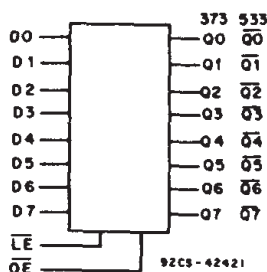


# CD54/74AC373, CD54/74AC533 CD54/74ACT373, CD54/74ACT533



Data sheet acquired from Harris Semiconductor  
SCHS289



## Octal Transparent Latch, 3-State

CD54/74AC/ACT373 - Non-Inverting

CD54/74AC/ACT533 - Inverting

### Type Features:

- Buffered inputs
- Typical propagation delay:  
4.3 ns @  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ ,  $C_L = 50\text{ pF}$

### FUNCTIONAL DIAGRAM

The RCA-CD54/74AC373 and CD54/74AC533 and the CD54/74ACT373 and CD54/74ACT533 octal transparent 3-state latches use the RCA ADVANCED CMOS technology. The outputs are transparent to the inputs when the Latch Enable ( $\overline{LE}$ ) is HIGH. When the Latch Enable ( $\overline{LE}$ ) goes LOW, the data is latched. The Output Enable ( $\overline{OE}$ ) controls the 3-state outputs. When the Output Enable ( $\overline{OE}$ ) is HIGH, the outputs are in the high-impedance state. The latch operation is independent of the state of the Output Enable.

The CD74AC/ACT373 and CD74AC/ACT533 are supplied in 20-lead dual-in-line plastic packages (E suffix) and in 20-lead dual-in-line small-outline plastic packages (M suffix). Both package types are operable over the following temperature ranges: Commercial (0 to  $70^\circ\text{C}$ ); Industrial ( $-40$  to  $+85^\circ\text{C}$ ); and Extended Industrial/Military ( $-55$  to  $+125^\circ\text{C}$ ).

The CD54AC/ACT373 and CD54AC/ACT533, available in chip form (H suffix), are operable over the  $-55$  to  $+125^\circ\text{C}$  temperature range.

### Family Features:

- Exceeds 2-kV ESD Protection - MIL-STD-883, Method 3015
- SCR-Latchup-resistant CMOS process and circuit design
- Speed of bipolar FAST<sup>®</sup>/AS/S with significantly reduced power consumption
- Balanced propagation delays
- AC types feature 1.5-V to 5.5-V operation and balanced noise immunity at 30% of the supply
- $\pm 24\text{-mA}$  output drive current
  - Fanout to 15 FAST<sup>®</sup> ICs
  - Drives 50-ohm transmission lines

\*FAST is a Registered Trademark of Fairchild Semiconductor Corp.

### TRUTH TABLE

Output Enable	Latch Enable	Data	AC/ACT373 Output	AC/ACT533 Output
L	H	H	H	L
L	H	L	L	H
L	L	I	L	H
L	L	h	H	L
H	X	X	Z	Z

#### Note:

L = Low voltage level  
H = High voltage level  
I = Low voltage level one set-up time prior to the high to low latch enable transition

h = High voltage level one set-up time prior to the high to low latch enable transition.  
X = Don't Care  
Z = High Impedance State

# Technical Data

## CD54/74AC373, CD54/74AC533

## CD54/74ACT373, CD54/74ACT533

### MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE ( $V_{CC}$ )	-0.5 to 6 V
DC INPUT DIODE CURRENT, $I_{IK}$ (for $V_i < -0.5$ V or $V_i > V_{CC} + 0.5$ V)	$\pm 20$ mA
DC OUTPUT DIODE CURRENT, $I_{OK}$ (for $V_o < -0.5$ V or $V_o > V_{CC} + 0.5$ V)	$\pm 50$ mA
DC OUTPUT SOURCE OR SINK CURRENT per Output Pin, $I_o$ (for $V_o > -0.5$ V or $V_o < V_{CC} + 0.5$ V)	$\pm 50$ mA
DC $V_{CC}$ or GROUND CURRENT ( $I_{CC}$ or $I_{GND}$ )	$\pm 100$ mA*
POWER DISSIPATION PER PACKAGE ( $P_D$ ):	
For $T_A = -55$ to $+100^\circ\text{C}$ (PACKAGE TYPE E)	500 mW
For $T_A = +100$ to $+125^\circ\text{C}$ (PACKAGE TYPE E)	Derate Linearly at 8 mW/ $^\circ\text{C}$ to 300 mW
For $T_A = -55$ to $+70^\circ\text{C}$ (PACKAGE TYPE M)	400 mW
For $T_A = +70$ to $+125^\circ\text{C}$ (PACKAGE TYPE M)	Derate Linearly at 6 mW/ $^\circ\text{C}$ to 70 mW
OPERATING-TEMPERATURE RANGE ( $T_A$ )	-55 to $+125^\circ\text{C}$
STORAGE TEMPERATURE ( $T_{stg}$ )	-65 to $+150^\circ\text{C}$
LEAD TEMPERATURE (DURING SOLDERING):	
At distance 1/16 $\pm$ 1/32 in. (1.59 $\pm$ 0.79 mm) from case for 10 s maximum	$+265^\circ\text{C}$
Unit inserted into PC board min. thickness 1/16 in. (1.59 mm) with solder contacting lead tips only	$+300^\circ\text{C}$

\*For up to 4 outputs per device; add  $\pm 25$  mA for each additional output.

### RECOMMENDED OPERATING CONDITIONS:

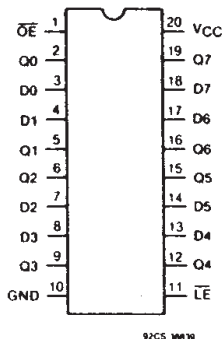
For maximum reliability, normal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range, $V_{CC}$ *: (For $T_A$ = Full Package-Temperature Range) AC Types ACT Types	1.5 4.5	5.5 5.5	V
DC Input or Output Voltage, $V_i$ , $V_o$	0	$V_{CC}$	V
Operating Temperature, $T_A$	-55	+125	$^\circ\text{C}$
Input Rise and Fall Slew Rate, $dt/dv$ at 1.5 V to 3 V (AC Types) at 3.6 V to 5.5 V (AC Types) at 4.5 V to 5.5 V (ACT Types)	0 0 0	50 20 10	ns/V ns/V ns/V

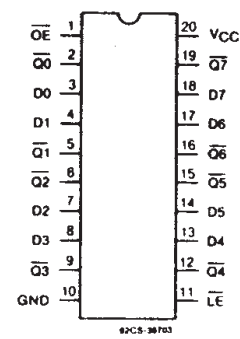
\*Unless otherwise specified, all voltages are referenced to ground.

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### TERMINAL ASSIGNMENT DIAGRAMS



CD54/74AC373, CD54/74ACT373



CD54/74AC533, CD54/74ACT533

# **CD54/74AC373, CD54/74AC533** **CD54/74ACT373, CD54/74ACT533**

**STATIC ELECTRICAL CHARACTERISTICS: AC Series**

CHARACTERISTICS	TEST CONDITIONS		V <sub>CC</sub> (V)	AMBIENT TEMPERATURE (T <sub>A</sub> ) - °C						UNITS
				+25		-40 to +85		-55 to +125		
	V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage V <sub>IH</sub>			1.5	1.2	—	1.2	—	1.2	—	V
			3	2.1	—	2.1	—	2.1	—	
			5.5	3.85	—	3.85	—	3.85	—	
Low-Level Input Voltage V <sub>IL</sub>			1.5	—	0.3	—	0.3	—	0.3	V
			3	—	0.9	—	0.9	—	0.9	
			5.5	—	1.65	—	1.65	—	1.65	
High-Level Output Voltage V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.05	1.5	1.4	—	1.4	—	1.4	—	V
		-0.05	3	2.9	—	2.9	—	2.9	—	
		-0.05	4.5	4.4	—	4.4	—	4.4	—	
		-4	3	2.58	—	2.48	—	2.4	—	
		-24	4.5	3.94	—	3.8	—	3.7	—	
	#, * {	-75	5.5	—	—	3.85	—	—	—	
		-50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.05	1.5	—	0.1	—	0.1	—	0.1	V
		0.05	3	—	0.1	—	0.1	—	0.1	
		0.05	4.5	—	0.1	—	0.1	—	0.1	
		12	3	—	0.36	—	0.44	—	0.5	
		24	4.5	—	0.36	—	0.44	—	0.5	
	#, * {	75	5.5	—	—	—	1.65	—	—	
		50	5.5	—	—	—	—	—	1.65	
Input Leakage Current I <sub>I</sub>	V <sub>CC</sub> or GND		5.5	—	±0.1	—	±1	—	±1	μA
3-State Leakage Current I <sub>OZ</sub>	V <sub>IH</sub> or V <sub>IL</sub> V <sub>O</sub> = V <sub>CC</sub> or GND		5.5	—	±0.5	—	±5	—	±10	μA
Quiescent Supply Current, MSI I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	—	8	—	80	—	160	μA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

\*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

Technical Data

# CD54/74AC373, CD54/74AC533 CD54/74ACT373, CD54/74ACT533

## STATIC ELECTRICAL CHARACTERISTICS: ACT Series

CHARACTERISTICS		TEST CONDITIONS		V <sub>CC</sub> (V)	AMBIENT TEMPERATURE (T <sub>A</sub> ) - °C						UNITS
					+25		-40 to +85		-55 to +125		
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage	V <sub>IH</sub>			4.5 to 5.5	2	—	2	—	2	—	V
Low-Level Input Voltage	V <sub>IL</sub>			4.5 to 5.5	—	0.8	—	0.8	—	0.8	V
High-Level Output Voltage	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub> # , * {	-0.05	4.5	4.4	—	4.4	—	4.4	—	V
			-24	4.5	3.94	—	3.8	—	3.7	—	
			-75	5.5	—	—	3.85	—	—	—	
			-50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub> # , * {	0.05	4.5	—	0.1	—	0.1	—	0.1	V
			24	4.5	—	0.36	—	0.44	—	0.5	
			75	5.5	—	—	—	1.65	—	—	
			50	5.5	—	—	—	—	—	1.65	
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> or GND		5.5	—	±0.1	—	±1	—	±1	μA
3-State Leakage Current	I <sub>OZ</sub>	V <sub>IH</sub> or V <sub>IL</sub> V <sub>O</sub> = V <sub>CC</sub> or GND		5.5	—	±0.5	—	±5	—	±10	μA
Quiescent Supply Current, MSI	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	—	8	—	80	—	160	μA
Additional Quiescent Supply Current per Input Pin TTL Inputs High 1 Unit Load	ΔI <sub>CC</sub>	V <sub>CC</sub> -2.1		4.5 to 5.5	—	2.4	—	2.8	—	3	mA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

\*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

ACT INPUT LOADING TABLE

INPUT	UNIT LOAD*	
	ACT373	ACT533
$\overline{OE}$	0.87	0.87
$\overline{Dn}$	0.5	0.5
$\overline{LE}$	0.8	0.8

\*Unit load is  $\Delta I_{CC}$  limit specified in Static Characteristics Chart, e.g., 2.4 mA max. @ 25°C.

# **CD54/74AC373, CD54/74AC533** **CD54/74ACT373, CD54/74ACT533**

**PREREQUISITE FOR SWITCHING: AC Series**

CHARACTERISTICS	SYMBOL	V <sub>CC</sub> (V)	AMBIENT TEMPERATURE (T <sub>A</sub> ) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
LE Pulse Width	t <sub>w</sub>	1.5 3.3* 5†	44 4.9 3.5	— — —	50 5.6 4	— — —	ns
Setup Time Data to LE	t <sub>su</sub>	1.5 3.3 5	2 2 2	— — —	2 2 2	— — —	ns
Hold Time Data to LE	t <sub>H</sub>	1.5 3.3 5	33 3.7 2.6	— — —	38 4.2 3	— — —	ns

\*3.3 V: min. is @ 3 V

†5 V: min. is @ 4.5 V

**SWITCHING CHARACTERISTICS: AC Series; t<sub>r</sub>, t<sub>f</sub> = 3 ns, C<sub>L</sub> = 50 pF**

CHARACTERISTICS	SYMBOL	V <sub>CC</sub> (V)	AMBIENT TEMPERATURE (T <sub>A</sub> ) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Data to Qn 373	t <sub>PLH</sub> t <sub>PHL</sub>	1.5 3.3* 5†	— 3.1 2.2	96 10.8 7.7	— 3 2.1	106 11.9 8.5	ns
533	t <sub>PLH</sub> t <sub>PHL</sub>	1.5 3.3 5	— 3.8 2.7	119 13.4 9.5	— 3.7 2.6	131 14.7 10.5	ns
LE on Qn 373	t <sub>PLH</sub> t <sub>PHL</sub>	1.5 3.3 5	— 4.3 3.1	136 15.2 10.9	— 4.2 3	150 16.8 12	ns
533	t <sub>PLH</sub> t <sub>PHL</sub>	1.5 3.3 5	— 4.3 3.1	136 15.3 10.9	— 4.2 3	150 16.8 12	ns
Output Enable Times	t <sub>PZL</sub> t <sub>PZH</sub>	1.5 3.3 5	— 4.1 2.7	119 14.4 9.5	— 4 2.6	131 15.8 10.5	ns
Output Disable Times	t <sub>PLZ</sub> t <sub>PHZ</sub>	1.5 3.3 5	— 3.7 3	131 13.1 10.5	— 3.6 2.9	144 14.4 11.5	ns
Power Dissipation Capacitance	C <sub>PD</sub> §	—	63 Typ.		63 Typ.		pF
Min. (Valley) V <sub>OH</sub> During Switching of Other Outputs (Output Under Test Not Switching)	V <sub>OHV</sub> See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) V <sub>OL</sub> During Switching of Other Outputs (Output Under Test Not Switching)	V <sub>OLP</sub> See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C <sub>I</sub>	—	—	10	—	10	pF
3-State Output Capacitance	C <sub>O</sub>	—	—	15	—	15	pF

\*3.3 V: min. is @ 3.6 V  
max. is @ 3 V

†5 V: min. is @ 5.5 V  
max. is @ 4.5 V

§C<sub>PD</sub> is used to determine the dynamic power consumption, per latch.

P<sub>D</sub> = V<sub>CC</sub><sup>2</sup> f<sub>i</sub> (C<sub>PD</sub> + C<sub>L</sub>) where f<sub>i</sub> = input frequency

C<sub>L</sub> = output load capacitance

V<sub>CC</sub> = supply voltage.

Technical Data

# CD54/74AC373, CD54/74AC533 CD54/74ACT373, CD54/74ACT533

**PREREQUISITE FOR SWITCHING: ACT Series**

CHARACTERISTICS	SYMBOL	V <sub>CC</sub> (V)	AMBIENT TEMPERATURE (T <sub>A</sub> ) -°C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
LE Pulse Width	t <sub>w</sub>	5†	3.6	—	4	—	ns
Setup Time Data to LE	t <sub>su</sub>	5	2	—	2	—	ns
Hold Time Data to LE	t <sub>H</sub>	5	2.7	—	3	—	ns

†5 V: min. is @ 4.5 V

**SWITCHING CHARACTERISTICS: ACT Series; t<sub>r</sub>, t<sub>f</sub> = 3 ns, C<sub>L</sub> = 50 pF**

CHARACTERISTICS	SYMBOL	V <sub>CC</sub> (V)	AMBIENT TEMPERATURE (T <sub>A</sub> ) -°C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Data to Q <sub>n</sub> 373	t <sub>PLH</sub>	5†	2.7	9.5	2.6	10.4	ns
533	t <sub>PHL</sub>		3	10.4	2.9	11.4	
LE to Q <sub>n</sub> 373 533	t <sub>PLH</sub> t <sub>PHL</sub>	5	3.1	11.4	3	12.5	ns
Output Enable Times	t <sub>PZL</sub> t <sub>PZH</sub>	5	3.5	12.3	3.4	13.5	ns
Output Disable Times	t <sub>PLZ</sub> t <sub>PHZ</sub>	5	3.2	11.4	3.1	12.5	ns
Power Dissipation Capacitance	C <sub>PD</sub> §	—	63 Typ.		63 Typ.		pF
Min. (Valley) V <sub>OH</sub> During Switching of Other Outputs (Output Under Test Not Switching)	V <sub>OHV</sub> See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) V <sub>OL</sub> During Switching of Other Outputs (Output Under Test Not Switching)	V <sub>OLP</sub> See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C <sub>I</sub>	—	—	10	—	10	pF
3-State Output Capacitance	C <sub>O</sub>	—	—	15	—	15	pF

†5 V: min. is @ 5.5 V  
max. is @ 4.5 V

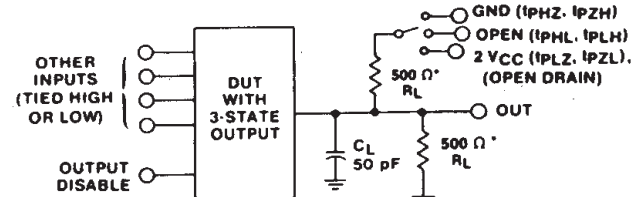
§C<sub>PD</sub> is used to determine the dynamic power consumption, per latch.

$P_D = V_{CC}^2 f_i (C_{PD} + C_L) + V_{CC} \Delta I_{CC}$  where  $f_i$  = input frequency  
C<sub>L</sub> = output load capacitance  
V<sub>CC</sub> = supply voltage.

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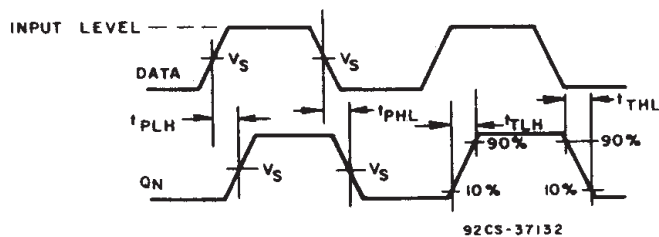
The diagram shows two sets of waveforms. The top set, labeled "OTHER OUTPUTS", shows a solid line switching between  $V_{OH}$  and  $V_{OL}$  levels, with dashed lines indicating the transition times. The bottom set, labeled "OUTPUT UNDER TEST", shows a solid line switching between  $V_{OH}$  and  $V_{OL}$  levels, with dashed lines indicating the transition times. The  $V_{OH}$  level is further divided into  $V_{OH}$  and  $V_{OH_V}$ , and the  $V_{OL}$  level is further divided into  $V_{OL_P}$  and  $V_{OL}$ .

- 92CS-42406**

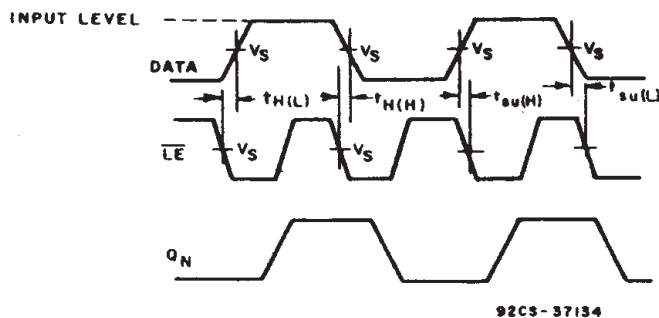


92CM-42405

**Fig. 2 - Three-state propagation delay waveforms and test circuit.**



**Fig. 4 - Latch enable propagation delays.**



	CD54/74AC	CD54/74ACT
Input Level	V <sub>CC</sub>	3 V
Input Switching Voltage, V <sub>s</sub>	0.5 V <sub>CC</sub>	1.5 V
Output Switching Voltage, V <sub>s</sub>	0.5 V <sub>CC</sub>	0.5 V <sub>CC</sub>

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CD54AC373F3A	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
CD54ACT373F3A	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
CD54ACT533F3A	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
CD74AC373E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74AC373EE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74AC373M	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC373M96	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC373M96E4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC373ME4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT373E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74ACT373EE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74ACT373M	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT373M96	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT373M96E4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT373ME4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



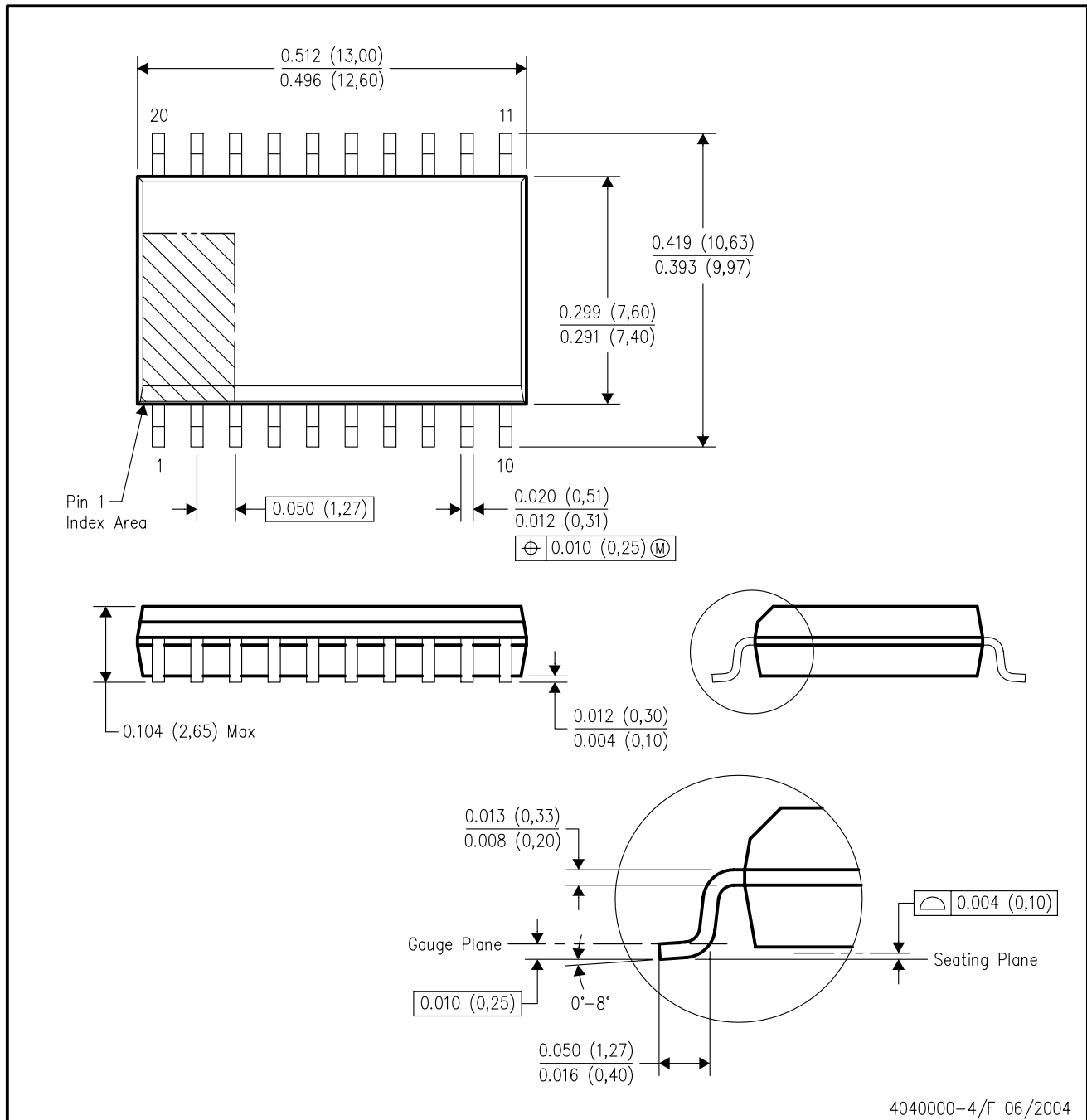
14/18 Pin Only  
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

## DW (R-PDSO-G20)

## PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MS-013 variation AC.

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